



SOITEC STRENGTHENS SALES TEAM WITH KEY APPOINTMENTS

Group names worldwide and Asia sales VPs to maximize customer commitment and increase opportunities for collaboration

Bernin, France — April 8, 2009 — Soitec (*Euronext Paris*), the world's leading supplier of silicon-on-insulator (SOI) wafers and other engineered substrates used for the microelectronics industry, today announced that the company has made key appointments to its sales team, who will drive its worldwide strategy and focus more closely on customer collaboration. Thomas Piliszcuk was named senior vice-president of worldwide sales, and Christophe Maleville was promoted to vice-president, sales, Asia. Piliszcuk joins Soitec from KLA-Tencor, where he held several senior management positions over the past 15 years. Maleville has held key management positions and been a major technology and operations contributor within the Soitec Group for more than a decade.

Reporting to Paul Boudre, Chief Operating Officer of the Soitec Group, Piliszcuk is chartered with focusing on revenue growth and will play a prominent role in driving customers collaborations in the US, Asia and Europe. Worldwide sales and field application support teams report to him.

Reporting to Piliszcuk, Christophe Maleville, who has been with Soitec since its inception in 1993, has been promoted to vice-president, sales, Asia to drive the company's business in the region in close collaboration with the local teams in Japan, Taiwan, Singapore and China. Maleville will also be responsible for developing strategic industry partnerships in the Far East region.

“With their extensive technology expertise, leadership and demonstrated commitment to customers, Thomas and Christophe will be driving collaborations and customers satisfaction,” said Paul Boudre. “They have the depth of experience to ensure that our worldwide and Asia sales teams continue to deliver substrate solutions tailored to our customers' evolving design needs and manufacturing requirements.”

Before joining the Soitec Group, Thomas Piliszcuk was with KLA-Tencor, where most recently he was in charge of customer alliances and worldwide strategy, engaged in high-level customer relationships. During his tenure there, Piliszcuk also managed European operations, where he successfully implemented partnership and collaboration programs to achieve company growth objectives and develop new business opportunities. Thomas Piliszcuk received his Ph.D in Elementary Optics from the *Ruprecht-Karls-Universitat Heidelberg* in Germany and an electrical engineering degree from the *Gdansk Polytechnic University* in Poland.

Christophe Maleville joined Soitec shortly after the company's founding. He was a key member to the team collaborating with CEA-Leti on the early development and industrialization of the Smart Cut™ process and its application to volume production of SOI wafers. For the last several years, he has managed new SOI process developments and has overseen SOI technology transfer from R&D to production and customer qualification. More recently, he held the position of vice-president, SOI Products Platform at Soitec, working closely with key customers worldwide in order to ensure alignment of the company's product roadmap with industry needs. Maleville has authored or co-authored more than 30 papers on

SOI material manufacturing and metrology. He holds close to 20 patents, many that have contributed to enhancing the quality of SOI wafers, and others that have enabled the high-volume fabrication of the most advanced generations of SOI and other engineered substrates. Maleville holds a Ph.D. in Microelectronics from the *Institut Polytechnique de Grenoble* (INPG).

About the Soitec Group:

The Soitec Group is the world's leading innovator and provider of the engineered substrate solutions that serve as the foundation for today's most advanced microelectronic products. The group leverages its proprietary Smart Cut™ technology to engineer new substrate solutions, such as silicon-on-insulator (SOI) wafers, which became the first high-volume application for this proprietary technology. Since then, SOI has emerged as the material platform of the future, enabling the production of higher performing, faster chips that consume less power.

Today, Soitec produces more than 80 percent of the world's SOI wafers. Headquartered in Bernin, France, with two high-volume fabs on-site, Soitec has offices throughout the United States, Japan and Taiwan, and a new production site in the process of customers' qualification in Singapore.

Two other divisions, Picogiga International (Les Ulis) and Tracit Technologies (Bernin), complete the Soitec Group. Picogiga delivers advanced substrates solutions, including III-V epiwafers and gallium nitride (GaN)-based wafers, to the compound material world for the manufacture of high-frequency electronics and other optoelectronic devices. Tracit, on the other hand, provides thin-film layer transfer technologies used to manufacture advanced substrates for power ICs and Microsystems, as well as generic circuit transfer technology for applications such as image sensors and 3D-integration. Shares of the Soitec Group are listed on Euronext Paris. For more information, visit www.soitec.com.

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Press Contact:

Camille Darnaud-Dufour Tel (France): +33 (0) 6 79 49 51 43
E-mail: camille.darnaud-dufour@soitec.com

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